000894 C02 USA/ISM/HDP/CVD/JW Application No: 10/767,792 Page 2 of 3

## REMARKS

Claims 1-25 are pending in this application

Rejection Under 35 U.S.C. 102(b)

The Examiner rejected claims 1-25 under 35 U.S.C. 102 (b) as being anticipated by Weldon et al. (U.S. Patent no. 6,108,189).

However, the Examiner appears to have made an inadvertent error because Weldon et al., U.S. Patent no 6,108,189, is a parent of the present application, and thus, not prior art. Specifically, Weldon et al. patent is cited in the Cross-Reference section of the present application as follows:

This application is a continuation of U.S. Patent Application Serial No. 10/095,914, filed on 3/12/2002, entitled, "ELECTROSTATIC CHUCK HAVING COMPOSITE DIELECTRIC LAYER AND METHOD OF MANUFACTURE", which is a divisional of U.S. Patent Application Serial No. 09/596,108, filed on 6/16/2000, entitled, "DIELECTRIC COVERED ELECTROSTATIC CHUCK", which is a divisional of U.S. Patent Number 6,108,189, issued on 8/22/00, entitled "ELECTROSTATIC CHUCK HAVING IMPROVED GAS CONDUITS", which is a continuation-in-part of U.S. Patent Number 5,720,818, issued February 24, 1998, entitled, "Conduits for Flow of Heat Transfer Fluid to the Surface of an Electrostatic Chuck," by Weldon et al., all of which are incorporated herein by reference.

[Emphasis added]

Since the filing date of the present application is traced back entirely to the parent, the parent is not prior art. Thus, claims 1-25 are allowable in their entirety over the cited Weldon application.

000894 C02 USA/ISM/HDP/CVD/JW/ Application No: 10/767,792 Page 3 of 3

## CONCLUSION

The above-discussed amendments are believed to place the present application in condition for allowance. Should the Examiner have any questions regarding the above remarks, the Examiner is requested to telephone Applicant's representative at the number listed below.

Respectfully submitted,
JANAH & ASSOCIATES, P.C.

Date: February 3, 2006

Anhalada

Reg. No. 37,48

Please direct all telephone calls to: Ashok K. Janah at (415) 538-1555.

Please continue to send correspondence to:

Patent Department, M/S 2061 APPLIED MATERIALS, INC. P.O. Box 450A Santa Clara, California 95052.